

Bondline™ 2485 is a silver filled, electrically conductive epoxy adhesive. This premixed, frozen and solvent free adhesive is designed for microelectronic chip bonding.

“A Reliable and Responsive Adhesive Company.”

Adhesive Properties

Color:	Silver
Viscosity*:	30,000 cps
Work Life @ 25°C:	10 days
Hardness (Shore D):	90
Cure Options:	30 minutes @ 150°C or 1 hour @ 130°C
Service Temperature Range:	-55°C to 175°C
Thixotropic Index:	3.6
Lap Shear Strength @ 25°C(AI to AI)**:	3000 psi
@25°C(Au. to Au.)**:	2000 psi
Volume Resistivity:	.0001 ohm cm.
Thermal Conductivity:	2.57 W/mK
Specific Gravity:	4.1
Glass Transition Temperature (Tg)**:	78°C
Weight Loss (TGA) @ 105°C:	Nil
Mobile Ion Concentration:	Potassium: <5 Chloride: 220 Sodium: 45
Coefficient of Thermal Expansion**:	
Below Tg:	31 x 10 ⁻⁶ in/in/°C
Above Tg:	219 x 10 ⁻⁶ in/in/°C
Shelf Life:	10 days @ 25°C 6 months @ 5°C 1 year @ -40°C
Availability:	Net volume 1cc to 2.5cc, available in disposable 3cc syringes.

Adhesive properties are not intended to be used as specification limits.

* Brookfield DV II+, CP 51 Spindle, 5 rpm, 25°C

**Cured 1 hour @ 150°C



Electronic Adhesives, Inc.

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General Instructions for Adhesive Storage and Use

FROZEN STORAGE – Unless otherwise stated

This adhesive must be stored at (minus) –40°C (°F) or colder at all times. Storing this adhesive at temperatures warmer than (minus) –40°C (°F) may alter the adhesives' properties and shorten its work life. DO NOT RE-FREEZE adhesive that has already been thawed!

THAWING PROCESS

Adhesive must reach room temperature before use. Remove syringes from freezer. Place syringes on end for thawing. See chart below for thaw time based on syringe size.

SYRINGE SIZE	THAW TIME
1cc	5 minutes
3cc	10 minutes
5cc	15 minutes
10cc	20 minutes

**** NOTE:** To accelerate thaw time, place syringes in front of an air blower or fan. This will reduce the thaw time by approximately 50%. Remove all condensation from syringes prior to use.

SURFACE PREPARATION

Make sure that all surface areas to be bonded are free of any contamination. If parts have been solvent cleaned make sure solvent is dried before applying adhesive

APPLICATION

Check the work life of the adhesive, on the technical data sheet. Adhesives must be used within the work life time period. The adhesives' properties will change (usually thicken) if it is used past the allowable work life.

Apply adhesive using dispensing equipment of choice. Contact Bondline Technical Service with questions about dispensing adhesives.

CURE

Choose a Cure Option (time & temperature) from the Bondline technical data sheet. Preheat the oven to the temperature of the selected cure option. For optimum cure, do not deviate from the selected cure option. Be sure to allow additional time for holding fixtures to reach cure temperature. Avoid opening oven doors during cure. Large fixtures and/or multiple fixtures may require extended cure time.

SAFETY

Review the adhesive Material Safety Data Sheet (MSDS) before using. Refer to the MSDS in case of emergency. Always wear protective gloves and goggles while handling adhesives. Only work with adhesives in well-ventilated areas, with curing ovens vented outside. For industrial use only.

TECHNICAL SERVICE CONTACT

For recommendations and help with any aspect of adhesive applications please contact the Bondline Technical Service Department (408) 830-9200, or via email: info@bondline.net or visit our website, www.bondline.net

CAUTION: For industrial use only. People with sensitive skin may have a reaction to this adhesive. Avoid skin contact. Wash all areas with soap and water immediately if contact does occur. It is important to refer to Material Safety Data Sheet (MSDS) OSHA for more details.

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